

L Number	Hits	Search Text	DB	Time stamp
2	395450	@ad>20000921 or @20000921	USPAT; US-PGPUB	2003/03/19 15:14
1	1484	"decoupled plasma source" or DPS	USPAT; US-PGPUB	2003/03/19 15:15
3	1124	("decoupled plasma source" or DPS) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 15:15
4	539	plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))	USPAT; US-PGPUB	2003/03/19 15:16
5	14	((("decoupled plasma source" or DPS) not (@ad>20000921 or @20000921)) and (plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))))	USPAT; US-PGPUB	2003/03/19 15:30
-	104	438/707.ccls.	USPAT; US-PGPUB	2003/03/19 10:44
-	163021	plasma	USPAT; US-PGPUB	2003/03/19 10:44
-	376413	conductive	USPAT; US-PGPUB	2003/03/19 10:45
-	28	438/707.ccls. and plasma and conductive	USPAT; US-PGPUB	2003/03/19 10:45
-	25	(438/707.ccls. and plasma and conductive) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 10:49
-	3	438/707.ccls. and (plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi)))	USPAT; US-PGPUB	2003/03/19 10:53
-	63190	438/\$.ccls.	USPAT; US-PGPUB	2003/03/19 10:53
-	362	(plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.	USPAT; US-PGPUB	2003/03/19 10:53
-	296	((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 10:53
-	155564	etching	USPAT; US-PGPUB	2003/03/19 10:53
-	283	((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching	USPAT; US-PGPUB	2003/03/19 10:54
-	26535	etching with plasma	USPAT; US-PGPUB	2003/03/19 10:54
-	239	(((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma))	USPAT; US-PGPUB	2003/03/19 11:01
-	61	438/709.ccls.	USPAT; US-PGPUB	2003/03/19 11:01
-	5	(((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/709.ccls.	USPAT; US-PGPUB	2003/03/19 11:03
-	144	438/711.ccls.	USPAT; US-PGPUB	2003/03/19 11:03
-	20	(((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/711.ccls.	USPAT; US-PGPUB	2003/03/19 11:03
-	20	(((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/711.ccls.) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 11:24
-	552	438/714.ccls.	USPAT; US-PGPUB	2003/03/19 11:25
-	39	(((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/714.ccls.	USPAT; US-PGPUB	2003/03/19 11:25

-	39	((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/714.ccls.) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 11:43
-	560	438/720.ccls.	USPAT; US-PGPUB	2003/03/19 11:43
-	28	((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/720.ccls.	USPAT; US-PGPUB	2003/03/19 11:43
-	28	((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/720.ccls.) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 11:53
-	136	438/721.ccls.	USPAT; US-PGPUB	2003/03/19 11:53
-	25	((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/721.ccls.	USPAT; US-PGPUB	2003/03/19 11:53
-	25	((((plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and 438/\$.ccls.) not (@ad>20000921 or @20000921)) and etching) and (etching with plasma)) and 438/721.ccls.) not (@ad>20000921 or @20000921)	USPAT; US-PGPUB	2003/03/19 11:53
-	8	438/for.109.ccls.	EPO; JPO; DERWENT	2003/03/19 12:05
-	1902	438/for.117.ccls.	EPO; JPO; DERWENT	2003/03/19 12:05
-	2	438/for.117.ccls. and (plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi)))	EPO; JPO; DERWENT	2003/03/19 12:05
-	41	plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))	EPO; JPO; DERWENT	2003/03/19 12:08
-	19783	plasma with etching	EPO; JPO; DERWENT	2003/03/19 12:08
-	27	(plasma with (polysilicon and ("tungsten silicide" or tungsten or W or WSi))) and (plasma with etching)	EPO; JPO; DERWENT	2003/03/19 12:08